

ABSTRACT

A module that can not only achieve the reduction in size and manufacturing cost but also be impervious to noise due to electromagnetic waves, and a mounted structure using the same are provided. A module (1) includes a substrate (12) and a plurality of semiconductor packages (11a, 11b), each including a semiconductor chip (10), mounted on the substrate (12). Each of the plurality of semiconductor packages (11a, 11b) includes a first radio communication element (16) for transmitting and receiving a signal between the semiconductor chips (10) in the plurality of semiconductor packages (11a, 11b) by radio communication, and the first radio communication element (16) is constituted independently of the semiconductor chip (10).